**SCM Series**
SMD Common Mode Inductor
Size 9035



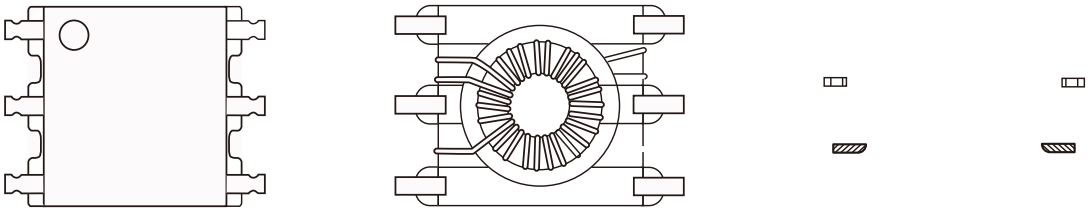
**FEATURES**

- High current capability up to 450 mA
- Rated voltage: 80 VDC (42 VAC)
- Flammability corresponding to UL 94 V-0
- Operating temperature -40~+125℃
- Quantity:1500pcs

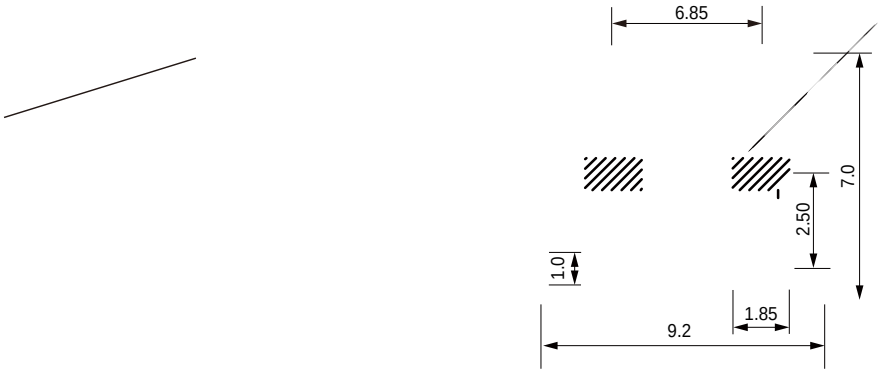
**APPLICATIONS**

- USB/CAN/FireWire etc.
- Signal and sensor lines
- Power supply systems
- Suppression of common mode noise

## Dimensions: [mm]



## Schematic:

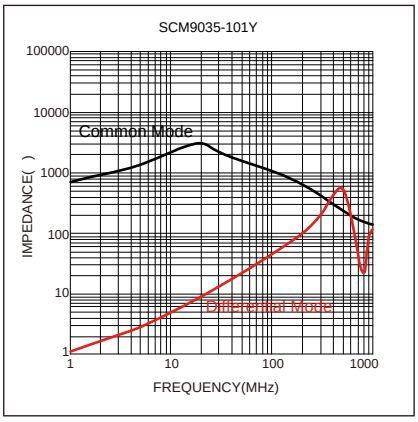



## Electrical Properties:

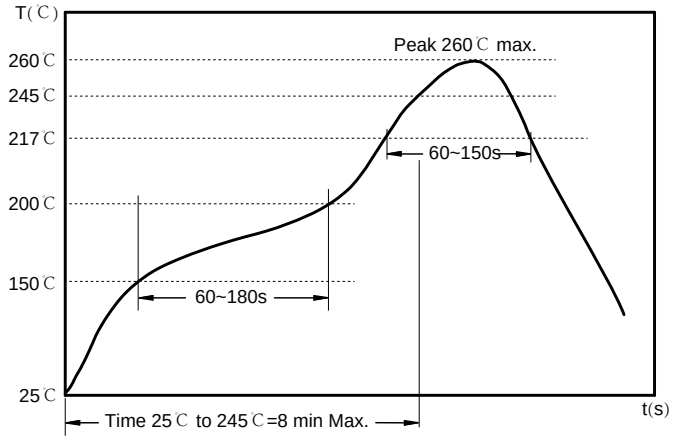
| Part No | Inductance @ 100KHz/0.1V (μH) 1-6=2-5=3-4 | Tolerance | DC Resistance Max. (Ω) 1-6=2-5=3-4 | Rated Current Max. (mA) 1-6=2-5=3-4 | Insulation Test Voltage Max. | Leakage Inductance @1MHz/1mA Typ. (nH) | Rated Voltage Typ. (V) | Peak Impedance Typ. (Ω) |
|---|---|---|---|---|---|---|---|---|
| SCM9035-101Y | 100 | +50%/-30% | 0.45 | 450 | 500 V(AC) | 94 | 80 | 3000 |

Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

# Typical Electrical Characteristics:



## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~180 sec.

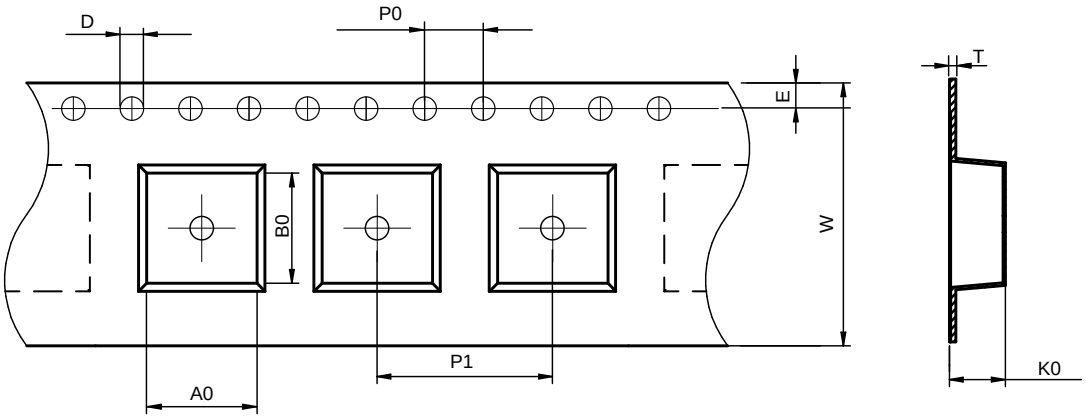
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

## Packaging Information:

### Tape Dimension:

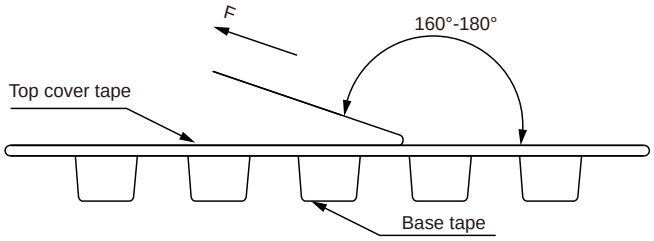



| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|---|
| SCM9035 | 6.90±0.1 | 9.30±0.1 | 1.5±0.1 | 4.0±0.1 | 12.0±0.1 | 16.0±0.3 | 3.8±0.1 | 1.75±0.1 | 0.40±0.05 |

### Product Marking:

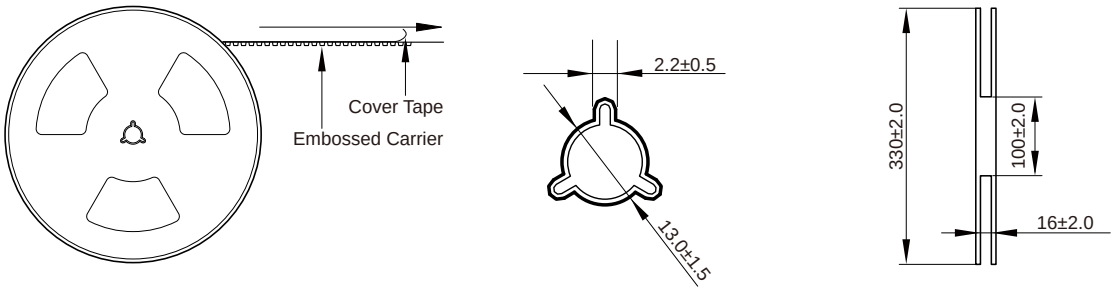
| Marking | Printing (Inductance) |
|---|---|

## Peel force of top cover tape:

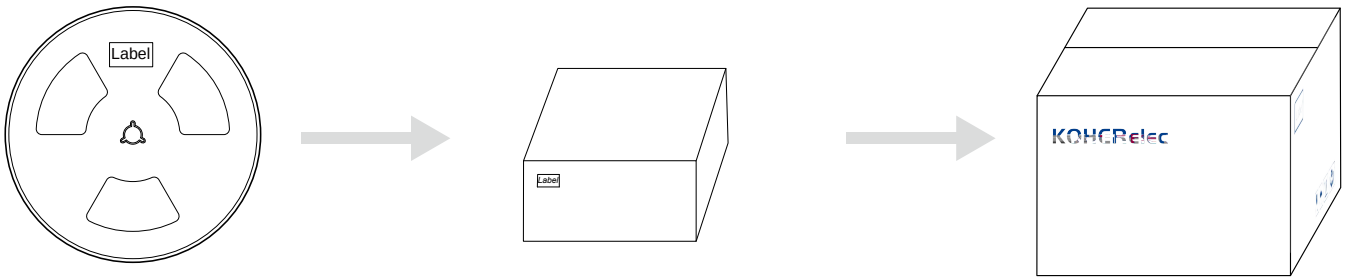



The peel force of top cover tape shall be between 0.2 to 1.17 N

## Reel Dimension：[mm]




## Packaging Quantity:




1500 Pcs/Reel

3 Reel /Inner box( 4500 Pcs)

3 Inner box/Carton box( 13.5K Pcs)

# Cautions and Warnings:

## Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

## Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.

## Conformal coating:

- The inductance value may change due to the high cure stress of the resin used for coating or molding.
- An open circuit may occur due to mechanical stress from the resin, its amount, cured shape, or operating conditions.
- Please exercise careful attention when selecting a resin for the coating or molding process.
- Prior to using the coating resin, please verify that no reliability issues are observed.
- When applying conformal coating for product protection, materials with a high shrinkage rate should be avoided.If such materials must be used, it is recommended to apply silicone around the inductor core in a closed loop to prevent the conformal coating from flowing into or penetrating the windings, thereby avoiding open-circuit failures caused by the coating's thermal stress.